Dual 3-Input "NOR" Gate Plus Inverter

The MC14000UB dual 3-input NOR gate plus inverter is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These complementary MOS logic gates find primary use where low power dissipation and/or high noise immunity is desired.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- · Logic Swing Independent of Fanout
- Pin-for-Pin Replacement for CD4000UB

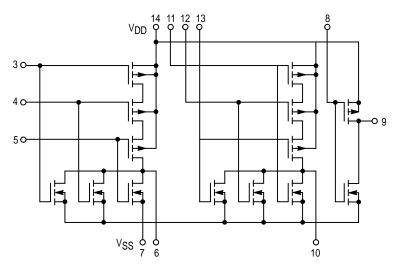
MAXIMUM RATINGS* (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage	- 0.5 to + 18.0	V
V _{in} , V _{out}	Input or Output Voltage (DC or Transient)	– 0.5 to V _{DD} + 0.5	V
l _{in} , l _{out}	Input or Output Current (DC or Transient), per Pin	± 10	mA
PD	Power Dissipation, per Package†	500	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

^{*} Maximum Ratings are those values beyond which damage to the device may occur. †Temperature Derating:

Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C Ceramic "L" Packages: – 12 mW/°C From 100°C To 125°C

CIRCUIT SCHEMATIC



MC14000UB



L SUFFIX CERAMIC CASE 632



P SUFFIX PLASTIC CASE 646

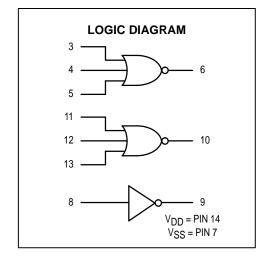


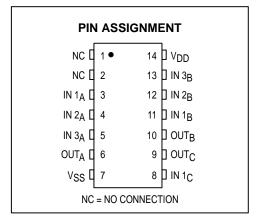
D SUFFIX SOIC CASE 751A

ORDERING INFORMATION

MC14XXXUBCP Plastic
MC14XXXUBCL Ceramic
MC14XXXUBD SOIC

 $T_A = -55^{\circ}$ to 125°C for all packages.





ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic			V _{DD}	VDD - 55°C		25°C		+ 125°C			
		Symbol	Vdc	Min	Max	Min	Тур #	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	VOL	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	VOH	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V _O = 4.5 Vdc) (V _O = 9.0 Vdc) (V _O = 13.5 Vdc)	"0" Level	V _{IL}	5.0 10 15	_ _ _	1.0 2.0 2.5	_ _ _	2.25 4.50 6.75	1.0 2.0 2.5	_ _ _	1.0 2.0 2.5	Vdc
$(V_O = 0.5 \text{ Vdc})$ $(V_O = 1.0 \text{ Vdc})$ $(V_O = 1.5 \text{ Vdc})$	"1" Level	VIH	5.0 10 15	4.0 8.0 12.5		4.0 8.0 12.5	2.75 5.50 8.25		4.0 8.0 12.5		Vdc
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source	ЮН	5.0 5.0 10 15	- 1.2 - 0.25 - 0.62 - 1.8	1111	- 1.0 - 0.2 - 0.5 - 1.5	- 1.7 - 0.36 - 0.9 - 3.5	1111	- 0.7 - 0.14 - 0.35 - 1.1	1111	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	l _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	_ _ _	0.25 0.5 1.0	_ _ _	0.0005 0.0010 0.0015	0.25 0.5 1.0	_ _ _	7.5 15 30	μAdc
Total Supply Current**† (Dynamic plus Quiescent, Per Gate, C _L = 50 pF)		lΤ	5.0 10 15			$I_T = (0.$	3 μΑ/kHz) f - 6 μΑ/kHz) f - 8 μΑ/kHz) f -	- I _{DD} /N			μAdc

[#]Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μ H (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.001 x the number of exercised gates per package.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.

^{**}The formulas given are for the typical characteristics only at 25°C.

[†]To calculate total supply current at loads other than 50 pF:

SWITCHING CHARACTERISTICS* (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V _{DD} Vdc	Min	Тур#	Max	Unit
Output Rise Time t _{TLH} = (3.0 ns/pF) C _L + 30 ns t _{TLH} = (1.5 ns/pF) C _L + 15 ns t _{TLH} = (1.1 ns/pF) C _L + 10 ns	[†] TLH	5.0 10 15	_ _ _	180 90 65	360 180 130	ns
Output Fall Time $t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_L + 25 \text{ ns}$ $t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_L + 12.5 \text{ ns}$ $t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_L + 9.5 \text{ ns}$	^t THL	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time tp_H, tp_H = (1.7 ns/pF) C _L + 30 ns tp_H, tp_H = (0.66 ns/pF) C _L + 22 ns tp_H, tp_H = (0.50 ns/pF) C _L + 15 ns	tPLH, [†] PHL	5.0 10 15	_ _ _	115 55 40	230 110 80	ns

^{*} The formulas given are for the typical characteristics only at 25°C.

[#]Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

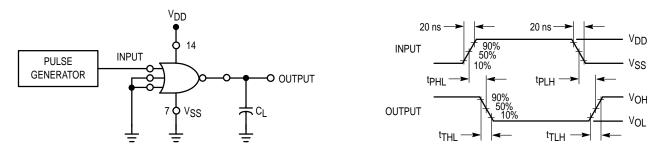


Figure 1. Switching Time Test Circuit and Waveforms

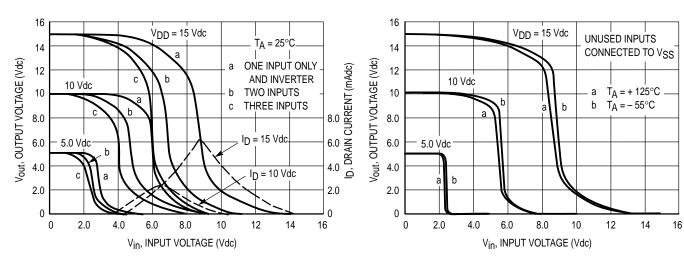
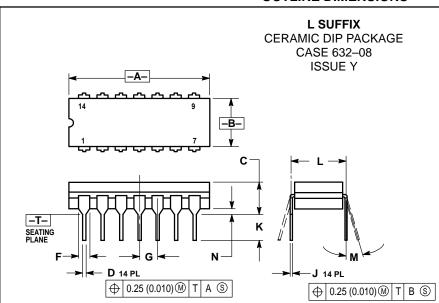


Figure 2. Typical Voltage and Current Transfer Characteristics

Figure 3. Typical Voltage Transfer Characteristics versus Temperature

OUTLINE DIMENSIONS



- IOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

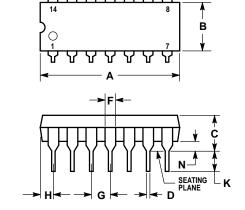
 3. DIMENSION I TO CENTER OF LEAD WHEN FORMED PARALLEL.

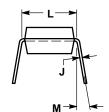
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.94	
В	0.245	0.280	6.23	7.11	
С	0.155	0.200	3.94	5.08	
D	0.015	0.020	0.39	0.50	
F	0.055	0.065	1.40	1.65	
G	0.100 BSC		2.54 BSC		
J	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62 BSC		
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

P SUFFIX

PLASTIC DIP PACKAGE CASE 646-06 ISSUE L





- NOTES:

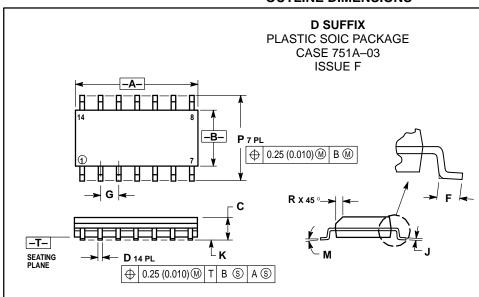
 1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.

 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 4. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54 BSC		
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.300 BSC		7.62 BSC		
M	0°	10°	0°	10°	
N	0.015	0.039	0.39	1.01	

OUTLINE DIMENSIONS



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Motorola data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and Marare registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

USA/EUROPE/Locations Not Listed: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. 1-800-441-2447 or 602-303-5454

MFAX: RMFAX0@email.sps.mot.com - TOUCHTONE 602-244-6609 INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center, 3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-81-3521-8315

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298





This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.